# SN54174, SN54175, SN54LS174, SN54LS175, SN54S174, SN54S175, SN74174, SN74LS174, SN74LS175, SN74LS175, SN74S174, SN74LS175, SN74S175, SN74S174, SN74LS175, SN74S174, SN74LS175, SN74S174, SN74LS175, SN74LS175, SN74LS175, SN74LS175, SN74LS175, SN74LS176, SN54LS176, SN

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'174, 'LS174, 'S174 . . . HEX D-TYPE FLIP-FLOPS '175, 'LS175, 'S175 . . . QUADRUPLE D-TYPE FLIP-FLOPS

- '174, 'LS174, 'S174 Contain Six Flip-Flops with Single-Rail Outputs
- '175, 'LS175, 'S175 Contain Four Flip-Flops with Double-Rail Outputs
- Three Performance Ranges Offered: See Table Lower Right
- Buffered Clock and Direct Clear Inputs
- Individual Data Input to Each Flip-Flop
- Applications include: Buffer/Storage Registers

Shift Registers
Pattern Generators

#### description

These monolithic, positive-edge-triggered flip-flops utilize TTL circuitry to implement D-type flip-flop logic. All have a direct clear input, and the '175, 'LS175, and 'S175 feature complementary outputs from each flip-flop.

Information at the D inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock input is at either the high or low level, the D input signal has no effect at the output.

These circuits are fully compatible for use with most TTL circuits.

FUNCTION TABLE (EACH FLIP-FLOP)

I	NPUTS		оит	PUTS
CLEAR	CLOCK	D	Q	ā۲
L	X	Х	L	Н
н	1	н	н	L
н	1	L	L	Н
н	L	х	αo	$\bar{\alpha}_0$

H = high level (steady state)

L = low level (steady state)

X = irrelevant

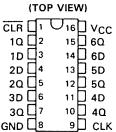
↑ = transition from low to high level

 ${\bf Q}_{\bf Q}$  = the level of  ${\bf Q}$  before the indicated steady-state input conditions were established.

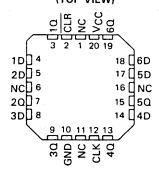
† = '175, 'LS175, and 'S175 only

	TYPICAL	TYPICAL
TYPES	MAXIMUM	POWER
11723	CLOCK	DISSIPATION
	FREQUENCY	PER FLIP-FLOP
'174, <b>'</b> 175	35 MHz	38 mW
'LS174, 'LS175	40 MHz	14 mW
'S174, 'S175	110 MHz	75 mW

SN54174, SN54LS174, SN54S174 . . . J OR W PACKAGE SN74174 . . . N PACKAGE SN74LS174, SN74S174 . . . D OR N PACKAGE



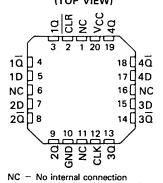
SN54LS174, SN54S174 . . . FK PACKAGE (TOP VIEW)



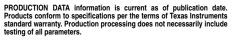
SN54175, SN54LS175, SN54S175 . . . J OR W PACKAGE SN74175 . . . N PACKAGE SN74LS175, SN74S175 . . . D OR N PACKAGE

> (TOP VIEW) U16 VCC CLR 1 10 🛮 2 15 40 10 □3 14 🛮 4 🗖 1D 🗆 4 13 4D 12 🛮 3D 2D 🗆 5 11 🛮 3 🗟 20 16 10 🛮 30 20 🗆 7 9 CLK

SN54LS175, SN54S175 . . . FK PACKAGE (TOP VIEW)



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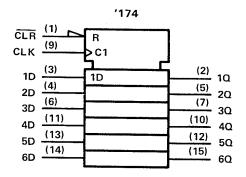


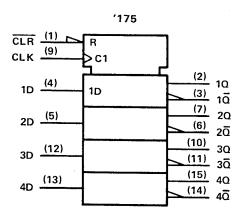


# SN54174, SN54175, SN54LS174, SN54LS175, SN54S174, SN54S175, SN74174, SN74LS174, SN74LS175, SN74S174, SN74S175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

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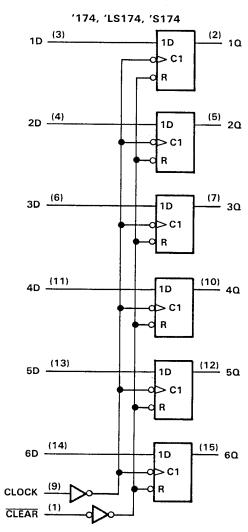
#### logic symbols†

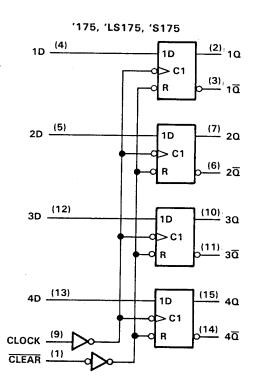




<sup>&</sup>lt;sup>†</sup>These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

#### logic diagrams (positive logic)





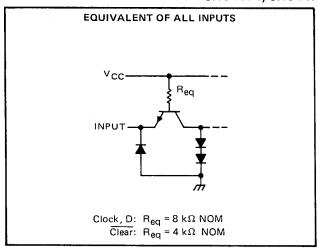
Pin numbers shown are for D, J, N, and W packages.

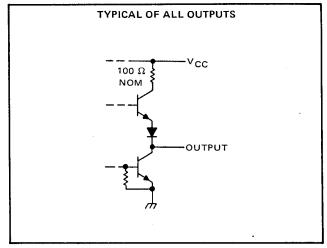


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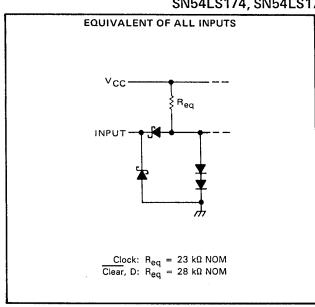
#### schematics of inputs and outputs

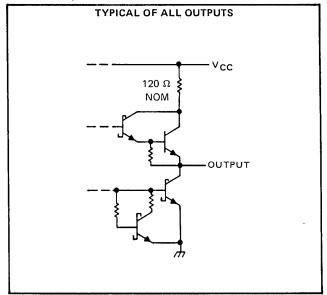
#### SN54174, SN54175, SN74174, SN74175



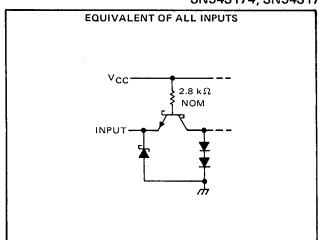


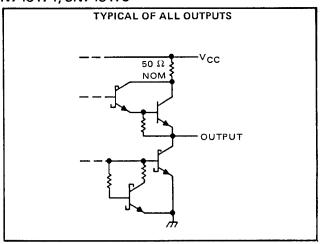
SN54LS174, SN54LS175, SN74LS174, SN74LS175





SN54S174, SN54S175, SN74S174, SN74S175







# SN54174, SN54175, SN74174, SN74175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	. <b></b>		′ V
Input voltage			ίV
Operating free-air temperature range: SN541	74, SN54175 Circuits		î°C
SN741	74, SN74175 Circuits	0°C to 70	)°C
Storage temperature range			)°C

#### recommended operating conditions

NOTE 1: Voltage values are with respect to network ground terminal.

		SN54	174, SN	54175	SN74	174, SN	74175	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>		4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH				-800			800	μΑ
Low-level output current, IOL				16			16	mA
Clock frequency, f <sub>clock</sub>		0		25	0		25	MHz
Width of clock or clear pulse, t <sub>W</sub>		20			20			ns
Setup time, t <sub>su</sub>	Data input	20			20			ns
Setup time, t <sub>su</sub>	Clear inactive-state	25			25			ns
Data hold time, t <sub>h</sub>		5			5			ns
Operating free-air temperature, TA		-55		125	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS <sup>†</sup>	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage		2			<b>V</b>
VIL	Low-level input voltage				0.8	>
VIK	Input clamp voltage	V <sub>CC</sub> = MIN, I <sub>I</sub> = -12 mA			-1.5	>
Vон	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -800 μA	2.4	3.4		٧
VOL	Low-level output voltage	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 16 mA		0.2	0.4	٧
Ιį	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V			1	mA
ΊΗ	High-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.4 V			40	μΑ
IIL	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V			-1.6	mA
1	Chart in it and the	SN SN	54' -20		-57	^
los	Short-circuit output current §	V <sub>CC</sub> = MAX	74' –18		-57	mA
laa	Cumple guerrant	VCC = MAX. See Note 2 '17	74	45	65	
1CC	Supply current	V <sub>CC</sub> = MAX, See Note 2 /17	75	30	45	mA

<sup>&</sup>lt;sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, I<sub>CC</sub> is measured after a momentary ground, then 4.5 V, is applied to clock.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ} \text{C}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f <sub>max</sub>	Maximum clock frequency		25	35		MHz
tPLH	Propagation delay time, low-to-high-level output from clear (SN54175, SN74175 only)	C <sub>L</sub> = 15 pF,		16	25	ns .
tPHL.	Propagation delay time, high-to-low-level output from clear	$R_L$ = 400 Ω, See Note 3		23	35	ns
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output from clock	See Note 3		20	30	ns
tPHL	Propagation delay time, high-to-low-level output from clock			24	35	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $<sup>^\</sup>ddagger$ All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25°C.

 $<sup>\</sup>$  Not more than one output should be shorted at a time.

## SN54LS174, SN54LS175, SN74LS174, SN74LS175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)				 	 	 7 V
Input voltage			<i></i>	 	 	 7.V
Operating free-air temperature range:	SN54LS174,	SN54LS175 C	Circuits .	 	 	–55°C to 125°C
	SN74LS174,	SN74LS175 (	Circuits .	 ·	 	 $1.0^{\circ}$ C to $70^{\circ}$ C
Storage temperature range						-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		SN	154LS1	74	SN	174LS1	74	
		12	154LS1	75	SI	174LS1	75	UNIT
		WIŃ	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V <sub>CC</sub>		4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH				-400			-400	μА
Low-level output current, IOL				4		·	8	mA
Clock frequency, fclock		0		30	0		30	MHz
Width of clock or clear pulse, t <sub>W</sub>		20			20			ns
Setup time, t <sub>su</sub>	Data input	20			20			ns
Setup time, t <sub>su</sub>	Clear inactive-state	25			25			ns
Data hold time, t <sub>h</sub>		5			5			ns
Operating free-air temperature, T <sub>A</sub>		-55		125	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TES	T CONDITIONS	t	_	N54LS1 N54LS1		_	N74LS N74LS		UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
VIH	High-level input voltage				2			2			٧
$v_{IL}$	Low-level input voltage						0.7			0.8	V
VIK	Input clamp voltage	V <sub>CC</sub> = MIN,	I <sub>1</sub> = -18 mA				-1.5			-1.5	V
V <sub>OH</sub>	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = V <sub>IL</sub> max	V <sub>IH</sub> = 2 V, , I <sub>OH</sub> = -400 μ,	Α	2.5	3.5		2.7	3.5		٧
V	Louise outros vales -	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	IOL = 4 mA		0.25	0.4		0.25	0.4	
VOL	Low-level output voltage	VIL = VIL max	•	IOL = 8 mA					0.35	0.5	٧
łį	Input current at maximum input voltage	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V				0.1			0.1	mA
Чн	High-level input current	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 2.7 V			· · · · · ·	20			20	μА
IJĽ	Low-level input current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V				-0.4			-0.4	mA
los	Short-circuit output current §	V <sub>CC</sub> = MAX			-20		-100	-20		-100	mA
loo	Supply current	V MAY	See Nete 2	'LS174		16	26		16	26	1
¹cc	Supply culterit	V <sub>CC</sub> = MAX,	See Note 2	'LS175		11	18		11	18	mA

<sup>1</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

#### switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CONDITIONS		'LS174			'LS175		
FARAMETER	LEST COMPLICIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
f <sub>max</sub> Maximum clock frequency		30	40		30	40		MHz
tplH Propagation delay time, low-to-high-level output from clear	C <sub>L</sub> = 15 pF,					20	30	ns
tphl Propagation delay time, high-to-low-level output from clear	$R_L = 2 k\Omega$ ,		23	35		20	30	ns
tPLH Propagation delay time, low-to-high-level output from clock	See Note 3		20	30		13	25	ns
tpHL Propagation delay time, high-to-low-level output from clock			21	30		16	25	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $<sup>^{\</sup>dagger}$  \$\frac{1}{4}\$ All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_{A} = 25^{\circ}\text{C}$ .

<sup>§</sup> Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, I<sub>CC</sub> is measured after a momentary ground, then 4.5 V, is applied to clock.

### SN54S174, SN54S175, SN74S174, SN74S175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)									 7	V
Input voltage									 5.5	V
Operating free-air temperature rang	e: SN5	4S174	, SN54S	175 Circuits					-55°C to 125°	С
-	SN7	4S174	, SN74S	175 Circuits					 . 0°C to 70°	C
Storage temperature range									65°C to 150°	C,

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		SN549	174, SN	54S175	SN74S	174, SN	74S175	LINIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>		4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH				-1			-1	mA
Low-level output current, IOL				20			20	mA
Clock frequency, f <sub>clock</sub>		0		75	0		75	MHz
Pulso width +	Clock	7			7			
Pulse width, t <sub>W</sub>	Clear	10			10			ns
Catura time t	Data input	5			5			
Setup time, t <sub>su</sub>	Clear inactive-state	5			5			ns
Data hold time, t <sub>h</sub>		3			3			ns
Operating free-air temperature, TA		-55		125	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage			2			V
VIL	Low-level input voltage					0.8	V
$v_{IK}$	Input clamp voltage	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA				-1.2	V
	High level automaticalisms	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V,	SN54S'	2.5	3.4		V
VOH	High-level output voltage	V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -1 mA	SN74S'	2.7	3.4		) V
V	Low level output voltage	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V,				0.5	V
VOL	Low-level output voltage	V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 20 mA				0.5	1
Ц	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V				1	mA
ЧΗ	High-level input current	V <sub>CC</sub> = MAX, V <sub>1</sub> = 2.7 V				50	μΑ
11L	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5 V				-2	mA
los	Short-circuit output current §	V <sub>CC</sub> = MAX		-40		-100	mA
la-	Constant	VMAY See Note 2	′174		90	144	mA
Icc	Supply current	V <sub>CC</sub> = MAX, See Note 2 '175			60	96	] '''A

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device

#### switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f <sub>max</sub>	Maximum clock frequency		75	110		MHz
tPLH	Propagation delay time, low-to-high-level $\overline{\mathbb{Q}}$ output from clear (SN54S175, SN74S175 only)	C <sub>L</sub> = 15 pF,		10	15	ns
tPHL.	Propagation delay time, high-to-low-level Q output from clear	$R_L = 280 \Omega$ , See Note 3		13	22	ns
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output from clock	See Note 3		8	12	ns
†PHL	Propagation time, high-to-low-level output from clock			11.5	17	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $<sup>\</sup>ddagger$ All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25°C. § Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, ICC is measured after a momentary ground, then 4.5 V, is

29-Sep-2011

#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
JM38510/01702BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	
JM38510/01702BFA	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	
JM38510/07105BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/07105BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
JM38510/07106BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30106B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/30106BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30106BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30107B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/30107BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30107BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30107SEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30107SFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SN54175J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	
SN54LS174J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54LS175J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54S174J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54S175J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN74174N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74175N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74175N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS174D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS174DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS174DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS174DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS174DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	



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Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN74LS174DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	, , , , , ,
SN74LS174J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	
SN74LS174N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS174N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS174NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS174NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS174NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS174NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS175D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS175DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS175DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS175DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS175DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS175DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS175J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	
SN74LS175N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS175N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS175NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS175NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS175NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS175NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74S174J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	





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Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN74S174N	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S174N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74S174NE4	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S175D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74S175DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74S175DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74S175DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	
SN74S175N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S175N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74S175NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SNJ54175J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	
SNJ54175W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	
SNJ54LS174FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS174J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS174W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS175FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS175J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS175W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S174FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54S174J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S174W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S175FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54S175J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S175W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW**: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE**: TI has discontinued the production of the device.

#### PACKAGE OPTION ADDENDUM



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(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# OTHER QUALIFIED VERSIONS OF SN54175, SN54LS174, SN54LS175, SN54LS175, SN54LS175, SN54S174, SN54S175, SN74175, SN74LS174, SN74LS175, SN74S174, SN74S175:

• Catalog: SN74175, SN74LS174, SN74LS175, SN54LS175, SN74S174, SN74S175

Military: SN54175, SN54LS174, SN54LS175, SN54S174, SN54S175

Space: SN54LS175-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS174DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS174NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS175DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS175NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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\*All dimensions are nominal

7 till difficilities die fromman							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS174DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS174NSR	SO	NS	16	2000	346.0	346.0	33.0
SN74LS175DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS175NSR	SO	NS	16	2000	346.0	346.0	33.0

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